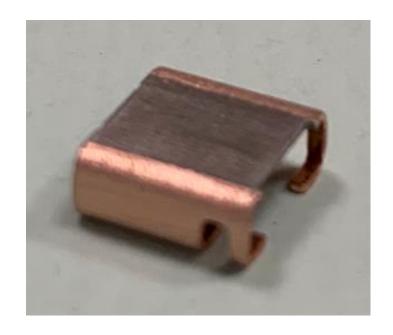
NEW New Power Applied Materials Co., Ltd.

High Power Shunt Resistor



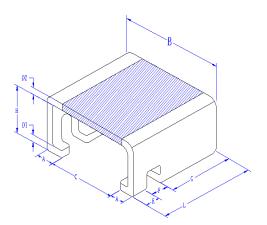
Document No: SR2725STD001A Issued data: 2016/05/24

Page: 1 of 5

Scope

This specification applies for metal type current shunt resistor.

Dimensions



Туре		Dimensions(mm)						
(inch size)	L	В	н	E	F	Α	D1	
SR2725 L50	6.60±0.25	6.90±0.15	2.40±0.2	0.7±0.2	1.0±0.2	1.90±0.2	0.45±0.1	
SR2725 1L0	6.60±0.25	6.90±0.15	2.40±0.2	0.7±0.2	1.0±0.2	1.90±0.2	0.35±0.1	
SR2725 2L0	6.60±0.25	6.90±0.15	2.40±0.2	0.7±0.2	1.0±0.2	1.90±0.2	0.55±0.1	
SR2725 3L0	6.60±0.25	6.90±0.15	2.40±0.2	0.7±0.2	1.0±0.2	1.90±0.2	0.35±0.1	
SR2725 4L0-5L0	6.60±0.25	6.90±0.15	2.40±0.2	0.7±0.2	1.0±0.2	1.90±0.2	0.35±0.1	

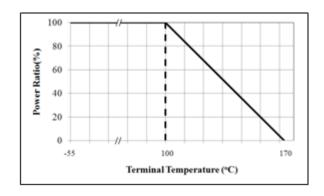
Features

- ♦ 5W permanent power, Inductance<3nH
- ♦ Internal heat resistance 15K/W
- ◆ Lead free, RoHs compliant for global applications and halogen free

Application

- ◆ Power modules
- ◆ Frequency converters
- ◆ Current sensor for power hybrid sources
- ♦ High current for automotive

Derating Curve





Document No: SR2725STD001A Issued data: 2016/05/24

Page: 2 of 5

Part Numbers

<u>SR 2725</u> <u>E</u> <u>F</u> <u>I</u> <u>1L00</u>

(1) (2) (3) (4) (5) (6)

(1)Series Name: SR (Shunt Resistor)

(2) Chip size: 2725(inch)

(3)Packaging Material: Emboss

(4)Resistance Tolerance: ±1% (F), ± 5% (J) (5)Power rating: I=5W, H=3W, E=2W

(6)Resistance Code: Ex: 1L0 means $1.0m\Omega$, etc.

Electrical Specification

Item	Power Rating	Resistance Range(m Ω)	Operation Temp. Range	TCR (PPM/°C)	Resistance Material
SR2725	5W	0.5	-55 ~ +170℃	±50	MnCuSn
SR2725	5W	1.0	-55~+170°C	±50	MnCu
SR2725	5W	2.0	-55~+170°C	±50	FeCrAl
SR2725	3W	3.0	-55~+170°C	±50	FeCrAl
SR2725	2W	4.0~5.0	-55~+170°℃	±50	FeCrAl

Performances

Environmental Performance

No.	Item	Test Condition	Specification
1	Short Time Overload	Loading 5 times rate power 5sec	ΔR: ±1%
2	Temperature Coefficient of Resistance (T.C.R.)	-20°C /+125°C. (JIS-C5202-5.2) $TCR \text{ (ppm/°C)} = \frac{\Delta R}{R \times \Delta t} \times 10^{6}$	Refer to electrical specification.
3	Moisture Resistance	The specimens shall be placed in a chamber and subjected to a relative humidity of 90~98% percent and a temperature of 25°C / 65°C 10 cycles (MIL-STD-202, Method 106)	ΔR: ±1%
4	High Temperature Exposure	The ship (mounted on board) is exposed in the heat chamber 125°C for 1000 hrs. (JIS-C5202-7.2)	ΔR: ±1%

Document No: SR2725STD001A Issued data: 2016/05/24

Page: 3 of 5

Performances

Environmental Performance

EUAILO	nvironmental Performance						
No.	Item	Test Condition	Specification				
5	Load Life	Apply rated power for 1000 hours with 1.5 hours ON and 0.5 hour OFF. (JIS-C5202-7.10)	ΔR: ±1%				
6	Rapid change of temperature	The chip (mounted on board) is exposed, -20±3°C (30min.)/+125±2°C (30min.) for 5 cycles. The following conditions as the following figure. (JIS-C5202-7.4) Ambient temperature 30 min. 30 min. 30 min. 2~3 min. 2~3 min. 2~3 min. 30 min. 3	ΔR: ±1%				

Remark:

a. The terminal electron temperature of component should below 100°C .

Function Performance

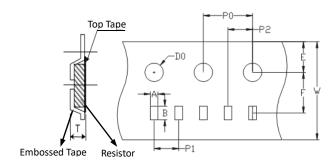
No.	Item	Test Condition	Specification
2	Solderability	The specimen chip shall be immersed into the flux specified in the solder bath $235\pm5^{\circ}\mathbb{C}$ for 2 ± 0.5 sec. It shall be immersed to a point 10mm from its root. (Sn96.5/Ag3.0/Cu0.5) (JIS-C5 202-6.11) Moiten solder Specimen SNID $h = 10 \text{ mm}$ $H = 10 \text{ mm}$ min.	Solder shall be covered 95% or more of the electrode area.

Document No: SR2725STD001A Issued data: 2016/05/24

Page: 4 of 5

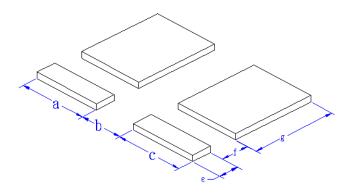
Tape Packaging Specifications

◆Embossed Plastic Tape Specifications



Туре		Carrier Dimensions (mm)								
Турс	Α	В	E	F	W	P0	P1	P2	D0	Т
SR2725	7.0±0.1	7.0±0.1	1.75±0.1	7.5±0.1	16.0±0.2	4.0±0.1	12.0±0.1	2.0 <u>±</u> 01	1.5±0.1	3.1±0.1

Recommended Pad Layout



Туре	Dimensions(mm)					
(inch size)	а	b	С	е	f	g
SR2725	2.9	2	2.9	0.9	1	5.6

Packaging

Size EIA (EIAJ)	2725
Standard Packing Quantity (pcs /Reel)	1400

Document No: SR2725STD001A Issued data: 2016/05/24

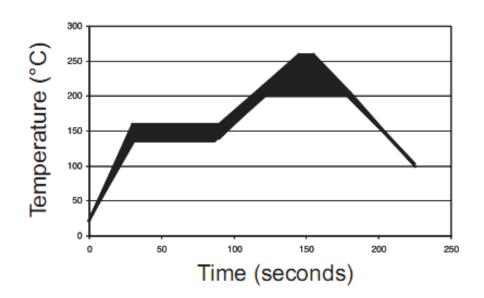
Page: 5 of 5

Storage Conditions

Temperature : 22^28° C, Humidity : $40^75\%$

Soldering Recommendations

- ◆ Peak reflow temperatures and durations:
 - IR Reflow Peak = 260°C max for 10 sec
 - Not suitable for wave soldering
- ◆ Recommended IR Reflow Profile:



ECN

Engineering Change Notice: The customer will be informed with ECN if there is significant modification on the characteristics and materials described in Approval Sheet.